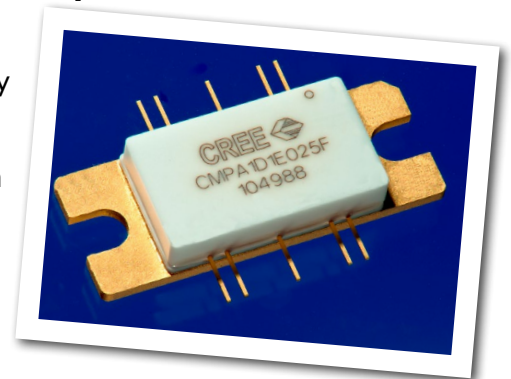


# CMPA1D1E025F

**25 W, 13.75 - 14.5 GHz, 40 V, Ku-Band GaN MMIC, Power Amplifier**

Cree's CMPA1D1E025F is a gallium nitride (GaN) High Electron Mobility Transistor (HEMT) based monolithic microwave integrated circuit (MMIC) on a silicon carbide substrate, using a 0.25  $\mu\text{m}$  gate length fabrication process. The Ku Band 25W MMIC is targeted for commercial Ku Band applications. It offers high gain and superior efficiency while meets OQPSK linearity required for Satcom applications at 3dB backed off Psat operations. This Ku Band MMIC is available in a 10 lead, 25 mm x 9.9 mm metal/ceramic flanged package.



## Typical Performance Over 13.75-14.5 GHz ( $T_c = 25^\circ\text{C}$ )

| Parameter              | 13.75 GHz | 14.0 GHz | 14.25 GHz | 14.5 GHz | Units |
|------------------------|-----------|----------|-----------|----------|-------|
| Small Signal Gain      | 26        | 27       | 27        | 26       | dB    |
| Linear Output Power    | 19        | 19       | 20        | 18       | W     |
| Power Gain             | 19.5      | 18.6     | 17.1      | 16.7     | dB    |
| Power Added Efficiency | 18        | 18       | 17        | 16       | %     |

Note<sup>1</sup>: Measured at -30 dBc, 1.6 MHz from carrier, in the CMPA1D1E025F-TB under OQPSK modulation, 1.6 Msps, PN23, Alpha Filter = 0.2.

## Features

- 26 dB Small Signal Gain
- 40 W Typical Pulsed  $P_{SAT}$
- Operation up to 40 V
- $P_{AVE} = 42$  dBm, linear power under OQPSK
- Class A/B high gain, high efficiency 50 ohm MMIC Ku Band high power amplifier

## Applications

- Satellite Communications Uplink

## Absolute Maximum Ratings (not simultaneous)

| Parameter                            | Symbol          | Rating    | Units    | Conditions                       |
|--------------------------------------|-----------------|-----------|----------|----------------------------------|
| Drain-source Voltage                 | $V_{DS}$        | 84        | $V_{DC}$ | 25°C                             |
| Gate-source Voltage                  | $V_{GS}$        | -10, +2   | $V_{DC}$ | 25°C                             |
| Power Dissipation                    | $P_{DISS}$      | 94        | W        |                                  |
| Storage Temperature                  | $T_{STG}$       | -55, +150 | °C       |                                  |
| Operating Junction Temperature       | $T_J$           | 225       | °C       |                                  |
| Maximum Forward Gate Current         | $I_{GMAX}$      | 10        | mA       | 25°C                             |
| Soldering Temperature <sup>1</sup>   | $T_S$           | 245       | °C       |                                  |
| Screw Torque                         | $\tau$          | 40        | in-oz    |                                  |
| Thermal Resistance, Junction to Case | $R_{\theta JC}$ | 1.5       | °C/W     | $P_{DISS} = 94 \text{ W}$ , 85°C |
| Case Operating Temperature           | $T_C$           | -40, +85  | °C       | CW, $P_{DISS} = 94 \text{ W}$    |

Note:

<sup>1</sup> Refer to the Application Note on soldering at [www.cree.com/products/wireless\\_appnotes.asp](http://www.cree.com/products/wireless_appnotes.asp)

## Electrical Characteristics (Frequency = 13.75 GHz to 14.5 GHz unless otherwise stated; $T_C = 25^\circ\text{C}$ )

| Characteristics                       | Symbol       | Min. | Typ. | Max. | Units  | Conditions                                                                                                            |
|---------------------------------------|--------------|------|------|------|--------|-----------------------------------------------------------------------------------------------------------------------|
| <b>DC Characteristics<sup>1</sup></b> |              |      |      |      |        |                                                                                                                       |
| Gate Threshold                        | $V_{GS(TH)}$ | -3.8 | -3.0 | -2.3 | V      | $V_{DS} = 10 \text{ V}$ , $I_D = 18.2 \text{ mA}$                                                                     |
| Gate Quiescent Voltage                | $V_Q$        | -    | -2.7 | -    | V      | $V_{DS} = 40 \text{ V}$ , $I_D = 240 \text{ mA}$                                                                      |
| Saturated Drain Current <sup>2</sup>  | $I_{DS}$     | 14.6 | 16.4 | -    | A      | $V_{DS} = 6.0 \text{ V}$ , $V_{GS} = 2.0 \text{ V}$                                                                   |
| Drain-Source Breakdown Voltage        | $V_{BD}$     | 84   | 100  | -    | V      | $V_{GS} = -8 \text{ V}$ , $I_D = 18.2 \text{ mA}$                                                                     |
| <b>RF Characteristics<sup>3</sup></b> |              |      |      |      |        |                                                                                                                       |
| Small Signal Gain                     | S21          | -    | 26   | -    | dB     | $V_{DD} = 40 \text{ V}$ , $I_{DQ} = 240 \text{ mA}$ , $P_{IN} = -20 \text{ dBm}$                                      |
| Input Return Loss                     | S11          | -    | -8   | -    | dB     | $V_{DD} = 40 \text{ V}$ , $I_{DQ} = 240 \text{ mA}$ , $P_{IN} = -20 \text{ dBm}$                                      |
| Output Return Loss                    | S22          | -    | -10  | -    | dB     | $V_{DD} = 40 \text{ V}$ , $I_{DQ} = 240 \text{ mA}$ , $P_{IN} = -20 \text{ dBm}$                                      |
| Output Mismatch Stress                | VSWR         | -    | -    | 5:1  | $\Psi$ | No damage at all phase angles, $V_{DD} = 40 \text{ V}$ , $I_{DQ} = 240 \text{ mA}$ , $P_{OUT} = 41 \text{ dBm}$ OQPSK |

Notes:

<sup>1</sup> Measured on-wafer prior to packaging.

<sup>2</sup> Scaled from PCM data.

<sup>3</sup> Measured in the CMPA1D1E025F-TB.

## Electrical Characteristics Continued... ( $T_c = 25^\circ\text{C}$ )

| Characteristics                             | Symbol   | Min. | Typ. | Max. | Units | Conditions                                                                   |
|---------------------------------------------|----------|------|------|------|-------|------------------------------------------------------------------------------|
| <b>RF Characteristics<sup>1,2,3,4</sup></b> |          |      |      |      |       |                                                                              |
| Power Added Efficiency                      | PAE1     | –    | 16.0 | –    | %     | $V_{DD} = 40\text{ V}$ , $I_{DQ} = 240\text{ mA}$ ,<br>Frequency = 13.75 GHz |
| Power Added Efficiency                      | PAE2     | –    | 14.0 | –    | %     | $V_{DD} = 40\text{ V}$ , $I_{DQ} = 240\text{ mA}$ ,<br>Frequency = 14.5 GHz  |
| Power Gain                                  | $G_{P1}$ | –    | 21.5 | –    | dB    | $V_{DD} = 40\text{ V}$ , $I_{DQ} = 240\text{ mA}$ ,<br>Frequency = 13.75 GHz |
| Power Gain                                  | $G_{P2}$ | –    | 19.0 | –    | dB    | $V_{DD} = 40\text{ V}$ , $I_{DQ} = 240\text{ mA}$ ,<br>Frequency = 14.5 GHz  |
| OQPSK Linearity                             | ACLR1    | –    | -38  | –    | dBc   | $V_{DD} = 40\text{ V}$ , $I_{DQ} = 240\text{ mA}$ ,<br>Frequency = 13.75 GHz |
| OQPSK Linearity                             | ACLR2    | –    | -37  | –    | dBc   | $V_{DD} = 40\text{ V}$ , $I_{DQ} = 240\text{ mA}$ ,<br>Frequency = 14.5 GHz  |

### Notes:

<sup>1</sup> Measured in the CMPA1D1E025F-TB.

<sup>2</sup> Under OQPSK modulated signal, 1.6 Msps, PN23, Alpha Filter = 0.2.

<sup>3</sup> Measured at  $P_{AVE} = 41\text{ dBm}$ .

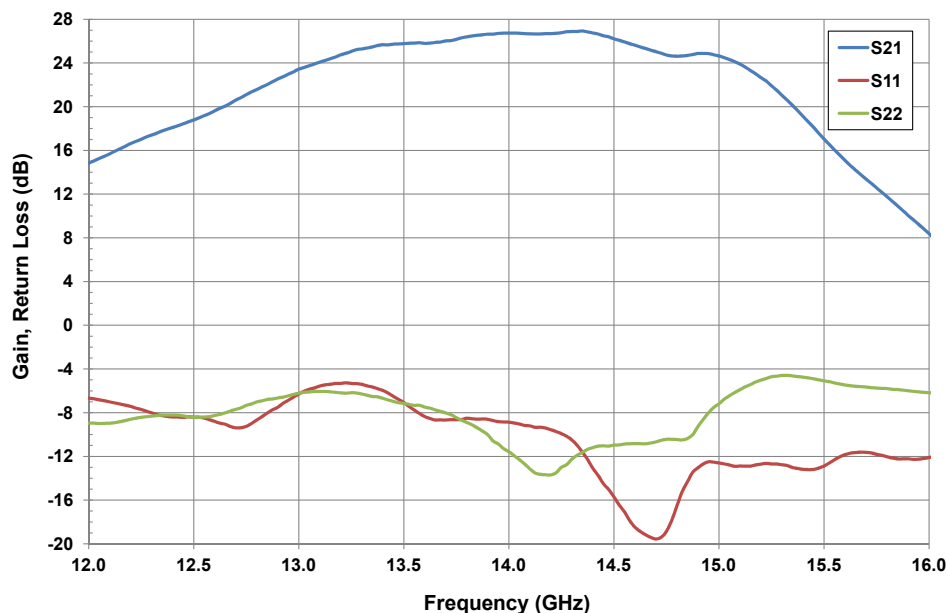
<sup>4</sup> Fixture loss de-embedded.

## Electrostatic Discharge (ESD) Classifications

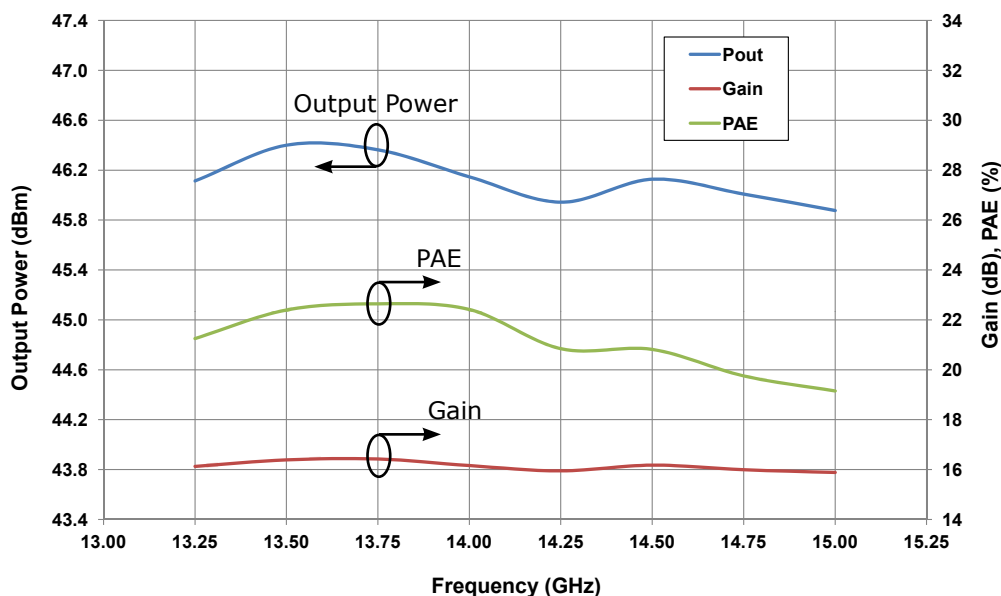
| Parameter           | Symbol | Class            | Test Methodology    |
|---------------------|--------|------------------|---------------------|
| Human Body Model    | HBM    | 1A (> 250 V)     | JEDEC JESD22 A114-D |
| Charge Device Model | CDM    | II (200 < 500 V) | JEDEC JESD22 C101-C |

## Typical Performance

**Figure 1. - Small Signal S-parameters  
CMPA1D1E025F in Test Fixture**  
 $V_{DD} = 40V$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^{\circ}C$

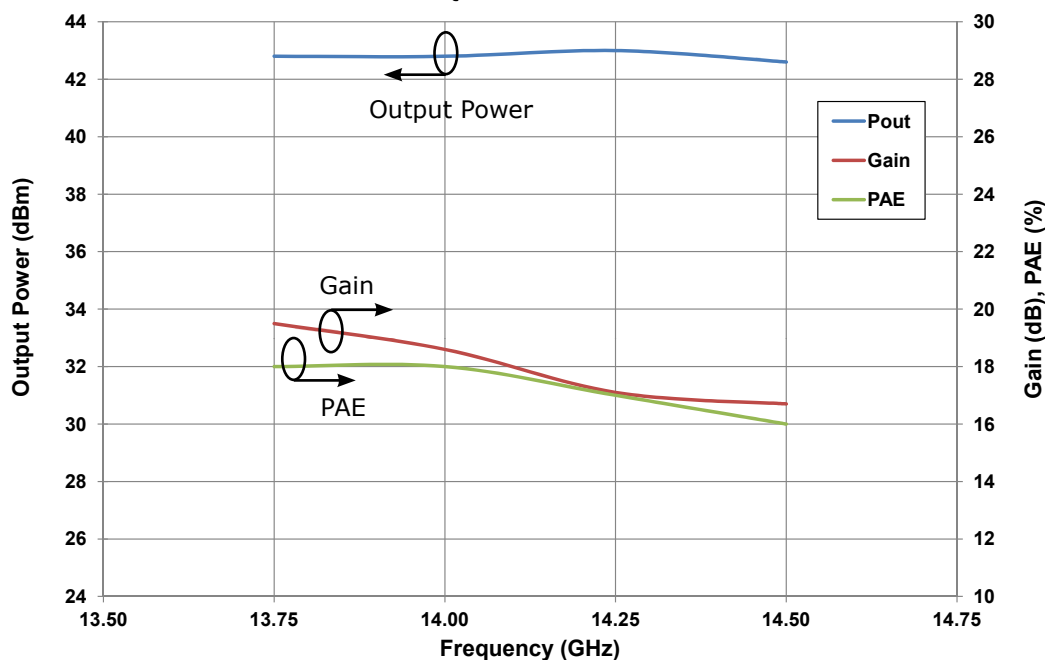


**Figure 2. - CMPA1D1E025F Pulsed @  $P_{IN} = 30\text{ dBm}$   
10% duty, 100  $\mu$ s pulse width**  
 $V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^{\circ}C$

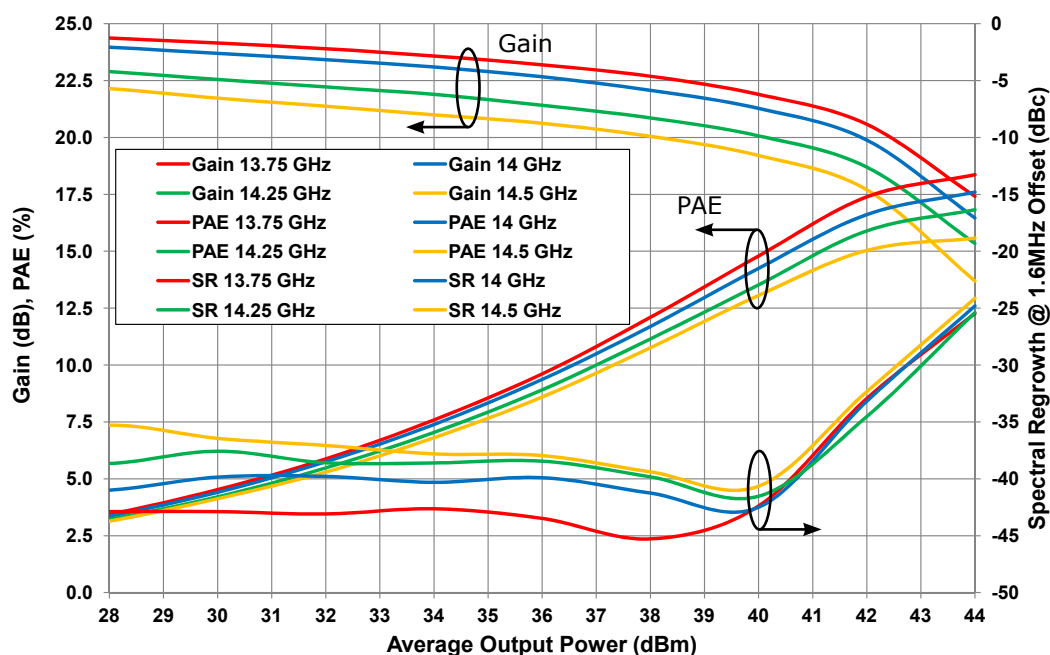


## Typical Performance

**Figure 3. - CMPA1D1E025F Modulated @ Spectral Regrowth = -30dBc, 1.6 MHz from Carrier**  
**1.6 Msps OQPSK Modulation**  
 $V_{DD} = 40V, I_{DQ} = 240\text{ mA}, T_{case} = 25^{\circ}C$



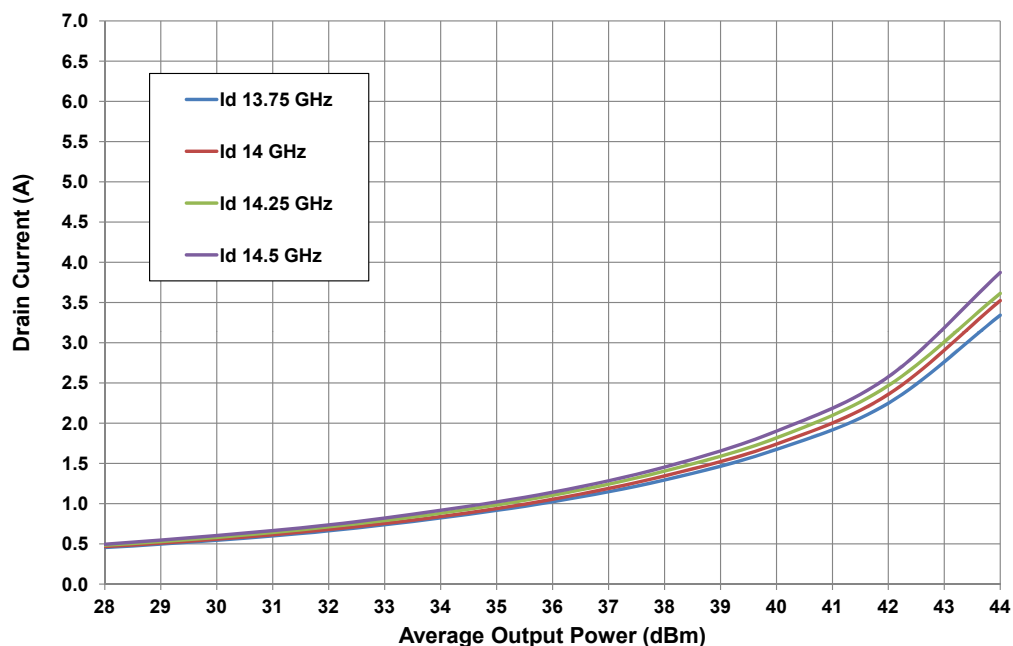
**Figure 4. - CMPA1D1E025F Modulated Power Sweep**  
**1.6 Msps OQPSK Modulation**  
 $V_{DD} = 40\text{ V}, I_{DQ} = 240\text{ mA}, T_{case} = 25^{\circ}C$



## Typical Performance

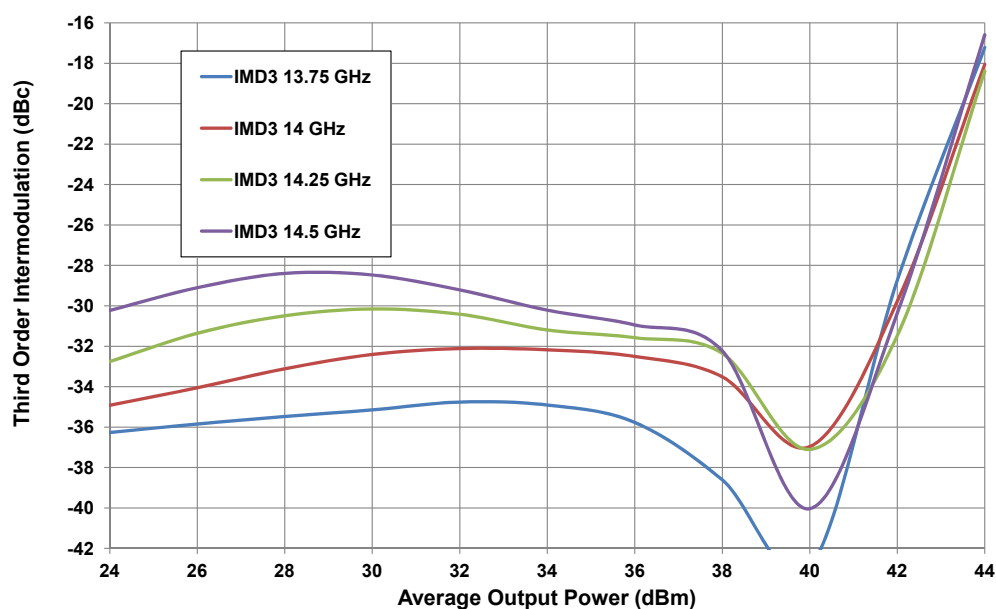
**Figure 5. - CMPA1D1E025F Modulated Power Sweep**  
**1.6 Msps OQPSK Modulation**

$V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^\circ\text{C}$



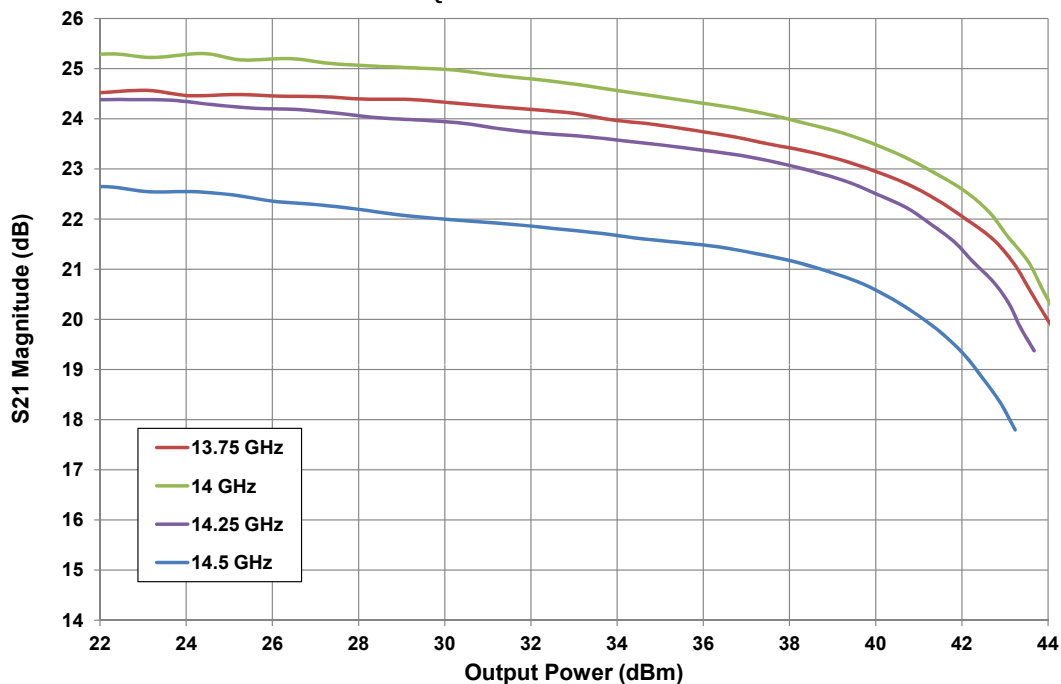
**Figure 6. - CMPA1D1E025F Two Tone Power Sweep**  
**IMD3 @ 1 MHz Carrier Spacing**

$V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^\circ\text{C}$

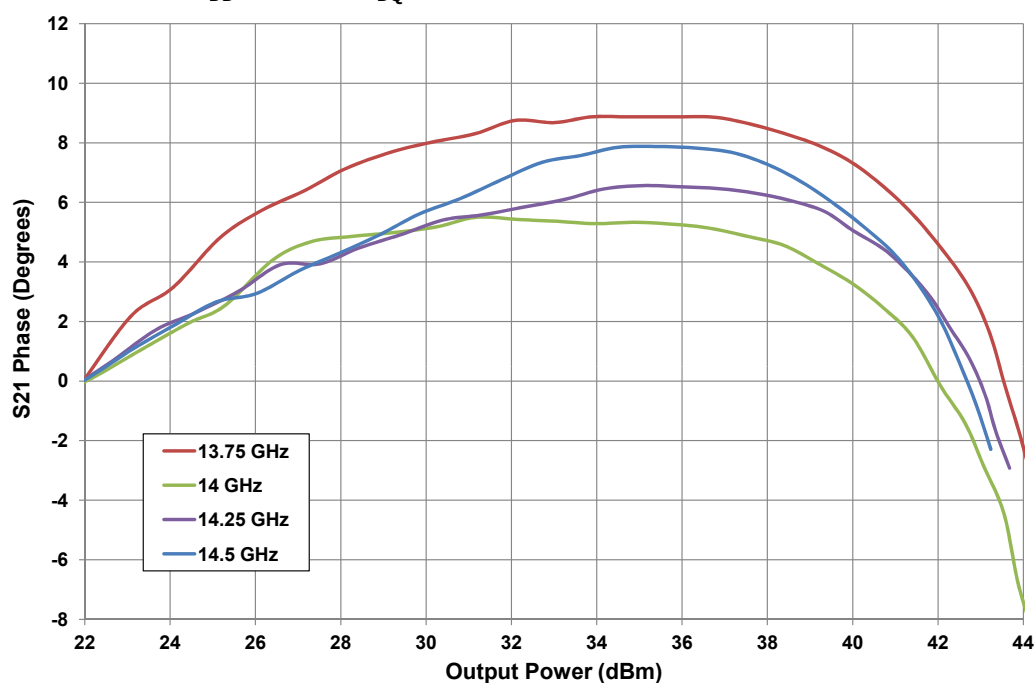


## Typical Performance

**Figure 7. - CMPA1D1E025F AM-AM**  
 $V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^\circ\text{C}$

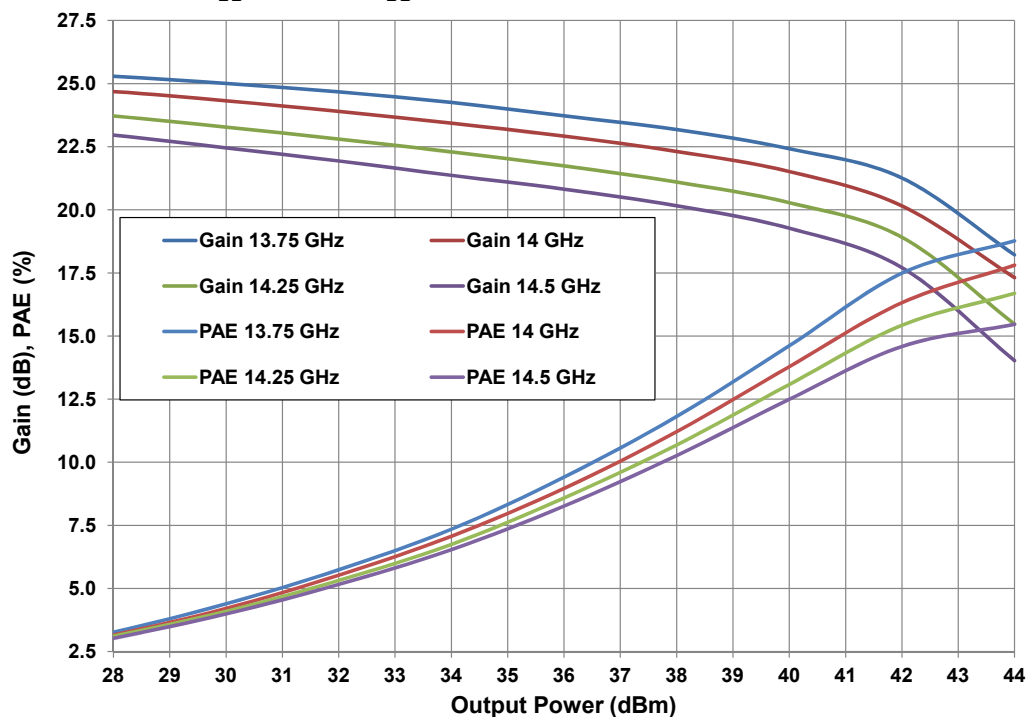


**Figure 8. - CMPA1D1E025F AM-PM**  
 $V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^\circ\text{C}$

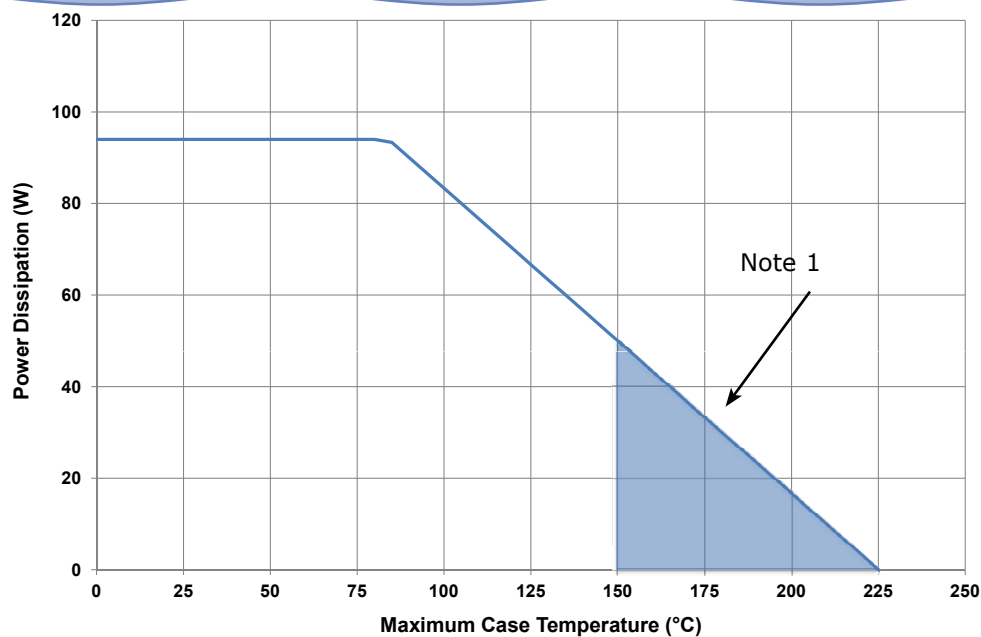


## Typical Performance

**Figure 9. - CMPA1D1E025F Gain and Power Added Efficiency vs CW Output Power**  
 $V_{DD} = 40\text{ V}$ ,  $I_{DO} = 240\text{ mA}$ ,  $T_{case} = 25^\circ\text{C}$



## CMPA1D1E025F Power Dissipation De-rating Curve



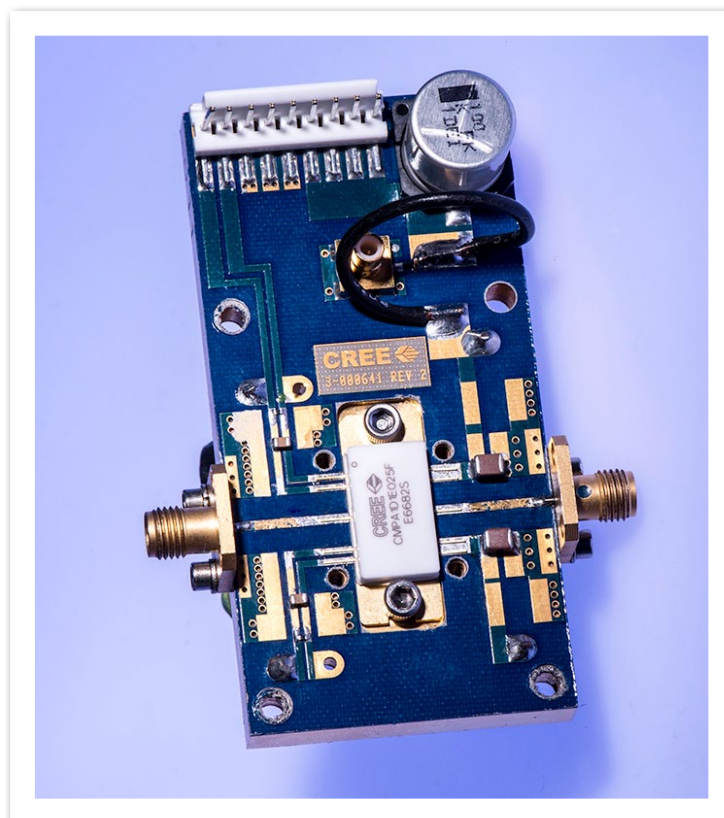
Note 1. Area exceeds Maximum Case Temperature (See Page 2).



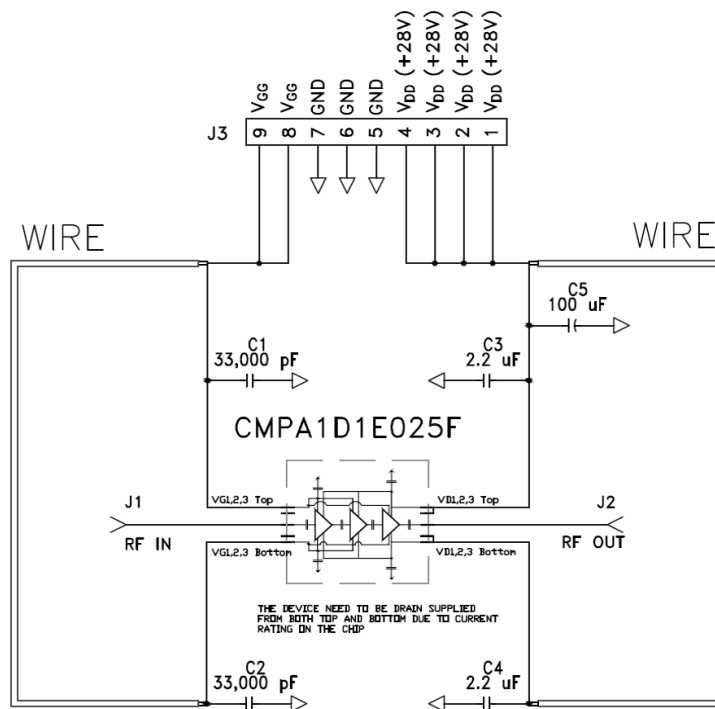
## CPMA1D1E025F-TB Demonstration Amplifier Circuit Bill of Materials

| Designator | Description                                                    | Qty |
|------------|----------------------------------------------------------------|-----|
| C5         | CAP ELECT 100UF 80V AFK SMD                                    | 1   |
| C1,C2      | CAP, 33000PF, 0805,100V, X7R                                   | 2   |
| C3,C4      | CAP, 2.2UF, 100V, 10%, X7R, 1210                               | 4   |
| J1,J2      | CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST, 20MIL | 2   |
| J4         | CONN, SMB, STRAIGHT JACK RECEPTACLE, SMT, 50 OHM, Au PLATED    | 1   |
| J3         | HEADER RT>PLZ .1CEN LK 9POS                                    | 1   |
| W1         | WIRE, BLACK, 22 AWG ~ 1.50"                                    | 1   |
| W2         | WIRE, BLACK, 22 AWG ~ 1.75"                                    | 1   |
| W3         | WIRE, BLACK, 22 AWG ~ 2.0"                                     | 1   |
|            | PCB, TEST FIXTURE, TACONICS RF35P, 20 MILS, 440208 PKG         | 1   |
|            | 2-56 SOC HD SCREW 1/4 SS                                       | 4   |
| -          | #2 SPLIT LOCKWASHER SS                                         | 4   |
| Q1         | CPMA1D1E025F                                                   | 1   |

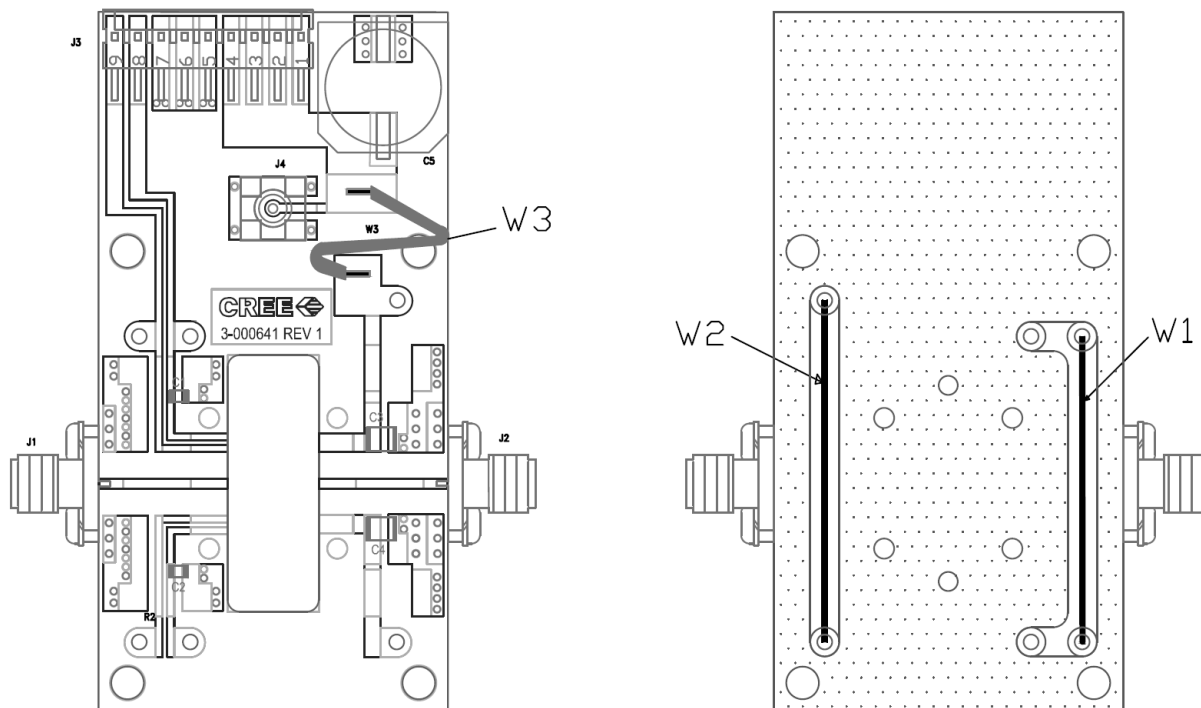
## CPMA1D1E025F-TB Demonstration Amplifier Circuit



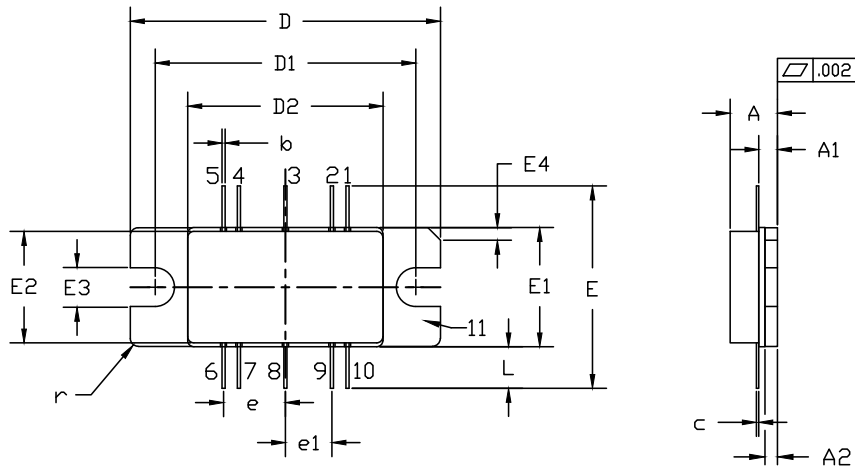
## CMPA1D1E025F-TB Demonstration Amplifier Circuit Schematic



## CMPA1D1E025F-TB Demonstration Amplifier Circuit Outline



## Product Dimensions CMPA1D1E025F (Package Type — 440208)



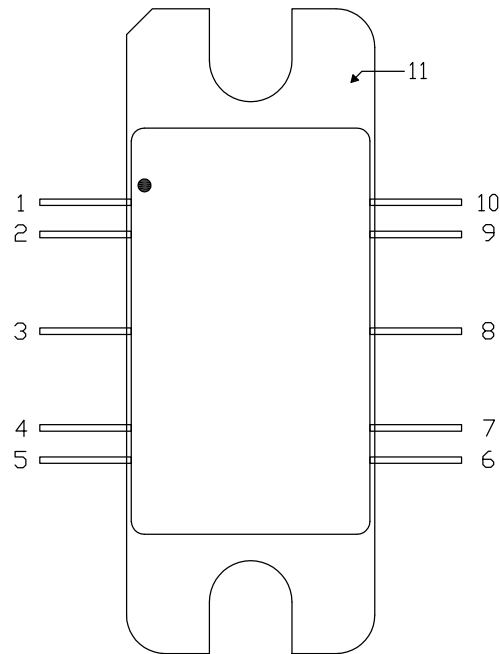
PIN 1: GATE BIAS 6: DRAIN BIAS  
 2: GATE BIAS 7: DRAIN BIAS  
 3: RF IN 8: RF OUT  
 4: GATE BIAS 9: DRAIN BIAS  
 5: GATE BIAS 10: DRAIN BIAS  
 11: SOURCE

### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M - 1994.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.

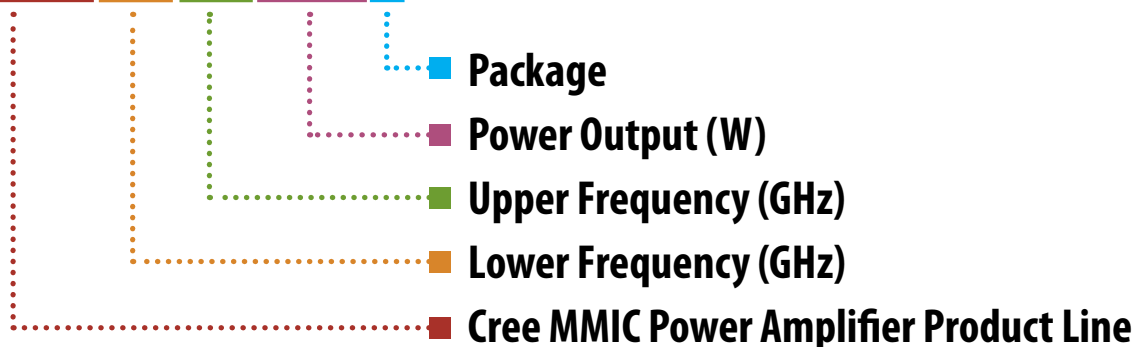
| DIM | INCHES |       | MILLIMETERS |       | NOTES       |
|-----|--------|-------|-------------|-------|-------------|
|     | MIN    | MAX   | MIN         | MAX   |             |
| A   | 0.148  | 0.168 | 3.76        | 4.27  |             |
| A1  | 0.055  | 0.065 | 1.40        | 1.65  |             |
| A2  | 0.035  | 0.045 | 0.89        | 1.14  |             |
| b   | 0.01   | TYP   | 0.254       | TYP   | 10x         |
| c   | 0.007  | 0.009 | 0.18        | 0.23  |             |
| D   | 0.995  | 1.005 | 25.27       | 25.53 |             |
| D1  | 0.835  | 0.845 | 21.21       | 21.46 |             |
| D2  | 0.623  | 0.637 | 15.82       | 16.18 |             |
| E   | 0.653  | TYP   | 16.59       | TYP   |             |
| E1  | 0.380  | 0.390 | 9.65        | 9.91  |             |
| E2  | 0.355  | 0.365 | 9.02        | 9.27  |             |
| E3  | 0.120  | 0.130 | 3.05        | 3.30  |             |
| E4  | 0.035  | 0.045 | 0.89        | 1.14  | 45° CHAMFER |
| e   | 0.200  | TYP   | 5.08        | TYP   | 4x          |
| e1  | 0.150  | TYP   | 3.81        | TYP   | 4x          |
| L   | 0.115  | 0.155 | 2.92        | 3.94  | 10x         |
| r   | 0.025  | TYP   | .635        | TYP   | 3x          |

| Pin Number | Qty        |
|------------|------------|
| 1          | Gate Bias  |
| 2          | NC         |
| 3          | RF In      |
| 4          | NC         |
| 5          | Gate Bias  |
| 6          | Drain Bias |
| 7          | Drain Bias |
| 8          | RF Out     |
| 9          | Drain Bias |
| 10         | Drain Bias |
| 11         | Source     |



## Part Number System

### CMPA1D1E025F



| Parameter                    | Value  | Units |
|------------------------------|--------|-------|
| Lower Frequency              | 13.5   | GHz   |
| Upper Frequency <sup>1</sup> | 14.5   | GHz   |
| Power Output                 | 25     | W     |
| Package                      | Flange | -     |

**Table 1.**

**Note<sup>1</sup>:** Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

| Character Code | Code Value                     |
|----------------|--------------------------------|
| A              | 0                              |
| B              | 1                              |
| C              | 2                              |
| D              | 3                              |
| E              | 4                              |
| F              | 5                              |
| G              | 6                              |
| H              | 7                              |
| J              | 8                              |
| K              | 9                              |
| Examples:      | 1A = 10.0 GHz<br>2H = 27.0 GHz |

**Table 2.**

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For more information, please contact:

Cree, Inc.  
4600 Silicon Drive  
Durham, North Carolina, USA 27703  
[www.cree.com/RF](http://www.cree.com/RF)

Sarah Miller  
Marketing & Export  
Cree, RF Components  
1.919.407.5302

Ryan Baker  
Marketing  
Cree, RF Components  
1.919.407.7816

Tom Dekker  
Sales Director  
Cree, RF Components  
1.919.407.5639

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### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

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